

REMARKS

Reconsideration is respectfully requested in view of any changes to the claims and the remarks herein. Please contact the undersigned to conduct a telephone interview in accordance with MPEP 713.01 to resolve any remaining requirements and/or issues prior to sending another Office Action. Relevant portions of MPEP 713.01 are included on the signature page of this amendment. This response is in supplement to applicants' response submitted on May 31, 2007.

Claims 7, 10, 41-43, 49, 51, 58-60 and 64-68 are allowed. Claim 69 is added herein. Support for the added claim is found throughout Applicants' specification in particular as shown below. Added claim 69 should be allowable for the same reasons that claims 7, 10, 41-43, 49, 51, 58-60 and 64-68 are allowed. Added claim 69 has identical wording to claim 2 of US 6,033,935.

Support For Added Claim 69 in the Specification

Support in the specification is in bold text in bold brackets **[text]** after each element of the claim.

Claim 69 [New] A method of effecting temporary connections **[Figs. 2 and 3 show that ends of elements 42 not in contact with element 87 are temporarily connected to contact locations on the surface of element 50. The sentence bridging pages 7-8 of the Specification teaches “The elongated conducting members 42 have ends 46 for probing contact locations on integrated circuit devices 48 of wafer 50. In the preferred embodiment, the workpiece is an integrated circuit such as a semiconductor chip or a semiconductor wafer having a plurality of chips.]** to free ends of at least a portion of a plurality of elongate spring contact elements **[elements 42 in Fig. 2 and 3 correspond to elements 198 in Fig. 28 which are elongated spring contact elements. The free ends of element 109 of Fig. 28 are the ends of element 198 not in contact with element 60]** mounted to and extending from an electronic component **[spring contact elements 198 are mounted to electronic component 60]**

such as a semiconductor device [Original claim 29 recites “silicon substrates”
Silicon is a semiconductor] the method comprising:

urging the electronic component against an interconnection substrate so that the free ends of at least a portion of the spring contact elements vertically contact selected ones of a corresponding plurality of terminals on the interconnection substrate [**Figs. 2 and 3 show that ends of elements 42 not in contact with element 87 are temporarily connected to contact locations on the surface of element 50.** The sentence bridging pages 7-8 of the Specification teaches “The elongated conducting members 42 have ends 46 for probing contact locations on integrated circuit devices 48 of wafer 50. In the preferred embodiment, the workpiece is an integrated circuit such as a semiconductor chip or a semiconductor wafer having a plurality of chips.];

providing a rigid planar member between the electronic component and the interconnection substrate [**Element 192 of Fig. 28 is a rigid planar member.**];

providing a plurality of guide holes in the rigid planar member [**Element 192 of Fig. 28 has a plurality guide holes 196**]; and

inserting the free ends of at least a portion of the spring contact elements extending through selected ones of the guide holes. [**The free ends of spring contact elements 198 of Fig. 28 extend through selected ones of the guide holes 196.**]

Added claim 69 has identical wording to claim 2 of US 6,033,935. Added claim 69 should be allowed for the same reasons for why claims 7, 10, 41-43, 49, 51, 58-60 and 64-68 are allowed.

In view of the changes to the claims and the remarks herein, the Examiner is respectfully requested to reconsider the above-identified application. If the Examiner wishes to discuss the application further, or if additional information would be required, the undersigned will cooperate fully to assist in the prosecution of this application.

Please charge any fee necessary to enter this paper and any previous paper to deposit account 09-0468.

If the above-identified Examiner's Action is a final Action, and if the above-identified application will be abandoned without further action by applicants, applicants file a Notice of Appeal to the Board of Appeals and Interferences appealing the final rejection of the claims in the above-identified Examiner's Action. Please charge deposit account 09-0468 any fee necessary to enter such Notice of Appeal.

In the event that this amendment does not result in allowance of all such claims, the undersigned attorney respectfully requests a telephone interview at the Examiner's earliest convenience.

MPEP 713.01 states in part as follows:

Where the response to a first complete action includes a request for an interview or a telephone consultation to be initiated by the examiner, ... the examiner, as soon as he or she has considered the effect of the response, should grant such request if it appears that the interview or consultation would result in expediting the case to a final action.

Respectfully submitted,

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